



Material Content Data Sheet



Sales Product Name		IPL60R210P6		Issued		19. July 2018		
MA#		MA001139732						
Package		PG-VSON-4-1		Weight*		190.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.148	4.28	4.28	42784	42784
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		67	
	non noble metal	zinc	7440-66-6	0.051	0.03		267	
	non noble metal	iron	7439-89-6	1.017	0.53		5341	
wire	non noble metal	copper	7440-50-8	41.300	21.69	22.26	216873	222548
	non noble metal	copper	7440-50-8	1.130	0.59	0.59	5935	5935
	encapsulation	organic material	carbon black	1333-86-4	0.211	0.11		1107
	plastics	epoxy resin	-	10.854	5.70		56993	
	inorganic material	silicondioxide	60676-86-0	94.310	49.52	55.33	495234	553334
leadfinish	non noble metal	tin	7440-31-5	2.397	1.26	1.26	12589	12589
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1323	1323
solder	noble metal	silver	7440-22-4	0.142	0.07		748	
	non noble metal	tin	7440-31-5	0.114	0.06		598	
	non noble metal	lead	7439-92-1	5.440	2.86	2.99	28565	29911
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		39	
	non noble metal	zinc	7440-66-6	0.030	0.02		158	
	non noble metal	iron	7439-89-6	0.601	0.32		3158	
	non noble metal	copper	7440-50-8	24.418	12.82	13.16	128221	131576
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com